Photolithographic Products

ABM High Resolution Mask Aligner and Exposure System









R&D, Rapid Prototyping, Pilot Production and Production



Microelectronic Devices

Electronic Packaging (Wafer Bumping and Wafer-level CSP)





Optoelectronic Devices (LED, Laser Diodes, Waveguide Arrays)



SAW Devices

MEMS and MOEMS



Nanoimprint Lithography

Biomedical and Photolysis Processes



Photolithographic Products ABM Mask Aligner

ABM, Inc. is the leading manufacturer of mask aligners and exposure systems for a wide variety of photolithography applications including Semiconductors, MEMS, LED, Displays, Optoelectronic Devices, Nanotechnology, and Electronic Packaging.

ABM mask aligner and exposure systems are used in Universities, R&D Centers, Pilot Production and Production facilities worldwide.

ABM, Inc. USA was established in 1986 in Silicon Valley California and has been serving the semiconductor industry for over 20+ years. The ABM, Inc. Group includes ABM, Inc., USA and ABM, Inc. Asia Pacific Ltd. with a global network of sales and service offices and representatives.

ABM Mask Aligner Model

Manual, Semi-Auto and Fully Auto System Frontside Alignment Backside Alignment Support 2"- 8" Round/Square Substrate and Pieces-part on standard, rough and patterned substrate Available 200-2000 Watt lamp Available NUV and DUV wavelength Selection of CCD Camera or Optical Microscope system Support Vacuum Contact, Soft/Hard Contact and Proximity mode exposure



ABM Manual Mask Aligner System



Model: ABM/6/350/NUV/DCCD/M

ABM Front Side Alignment System

Key Performance Features

Uniform Beam Size: 6" diameter/square Beam Uniformity:

- < ±1% over 2" Round Area
- < ±2% over 4" Round Area
- < ±3% over 6" Round Area

Printing Resolution:

< 0.5 micron for vacuum/hard contact (NUV exposure)

< 0.3 micron for vacuum/hard contact (DUV exposure) Alignment Accuracy : +/- 0.5 micron

Work with Positive, Negative and Thick photoresist, Up to 300 micron thick SU-8 with up to 10:1 aspect ratios Soft/Hard Contact, Vacuum Contact, and Proximity Printing

Main Specifications

6" Exposure Lightsource for G-, H-, I-Line wavelength output Work with 2", 3", 4", 6" (Round/Square substrate) and piece-parts

Adjustable wattage 2-Channel 350 Watt NUV Constant Intensity/Constant Power controlling power supplies. Option for 500, 1000 and 2,000 Watt DUV and NUV power supplies

Single/Split-field Dual CCD Camera alignment systems and Single/Split-field Microscope alignment system are available Upgradable to Double Side Exposure System



ABM Manual BSV/BSIR Mask Aligner System



Model: ABM/6/350/NUV/DCCD/BSV/M

ABM Double Side Alignment System

Key Performance Features

BackSide Alignment Accuracy : +/- 0.5 micror

Work with Positive, Negative and Thick photoresist, Up to 300 micron thick SU-8 with up to 10:1 aspect ratios Soft/Hard Contact, Vacuum Contact, and Proximity Printing Constant Power/Constant Intensity Controlling Power Supply

350 Watt 6" NUV Lightsource

(with broadband 365/400/436 nm mirrors) 365 nm Output Intensity – 20-22 mW/cm² 400 nm Output Intensity – 40-45 mW/cm² 436 nm Output Intensity – 10-12 mW/cm²

Main Specifications

6" Exposure Lightsource for G-, H-, I-Line wavelength output Work with 2", 3", 4", 6" (Round/Square substrate) and piece-parts

Adjustable wattage 2-Channel 350 Watt NUV Constant Intensity/Constant Power controlling power supplies. Option for 500, 1000 and 2,000 Watt DUV and NUV power supplies

Single/Split-field Dual CCD Camera alignment systems and Single/Split-field Microscope alignment system are available

Backside Infrared (BSIR) alignment system Backside Visible (BSV) alignment system

ABM Large Area Manual Mask Aligner System

Model: ABM/8/500/NUV/DCCD/M

ABM 8" Front Side Alignment System

Key Performance Features

Uniform Beam Size: 8" diameter/square Beam Uniformity: 500W 8" Light:

- < ±1% over 4" Square Area
- < ±2% over 6" Square Area
- < ±3% over 8" Square Are
- Printing Resolution:
 - < 0.5 micron for vacuum/hard contact (NUV exposure)
 - < 0.8 micron for soft contact
 - < 1 micron for 50 micron proximity gap
 - < 2 micron for 100 micron proximity gap
- Alignment Accuracy : +/- 0.5 micron

Work with Positive, Negative and Thick photoresist,

Up to 300 micron thick SU-8 with up to 10:1 aspect ratios

Constant Power/Constant Intensity Controlling Power Supply

965 nm Output Intensity – 18-20 mW/cm² 100 nm Output Intensity – 35-40 mW/cm² 136 nm Output Intensity – 8-10 mW/cm²

Main Specifications

8" Exposure Lightsource for G-, H-, I-Line wavelength output NUV or DUV wavelength Work with 2", 3" ,4", 6" (Round/Square subst and piece-parts

Single/Split-field Dual CCD Camera alignmer systems and Single/Split-field Microscope alignment system are available. Upgradable to Double Side Exposure System

ABM Semi-Auto Mask Aligner System

Model: ABM/6/350/NUV/DCCD/SA

ABM Front Side Semi-Auto Alignment System

Key Performance Features

Specificially for opto-electronic device and LED manufacturer with PLC control and touch panel monitor system. By pressing only one button to avoid the unnecessary operational error to complete the whole process and effectively increase the productivity and stablity.

b" Exposure Lightsource
Alignment Accuracy : +/- 0.5 micron.
Work with 2", 3", 4", 6" (Round/Square substrate) and piece-parts
Work with Positive, Negative and Thick photoresist,
Up to 300 micron thick SU-8 with up to 10:1 aspect ratios
Support for PSS process
Soft/Hard Contact, Vacuum Contact, and Proximity Printing
Constant Intensity/Constant Power controlling modes.
Upgradable to Double Side Exposure System

6" Exposure Lightsource for G-, H-, I-Line wavelength output

PLC control with Touch Panel Monitor System

Adjustable wattage 2-Channel 350 Watt NUV Constant Intensity/Constant Power controlling power supplies. Option for 500, 1000 and 2,000 Watt DUV and NUV power supplies.

Single/Split-field Dual CCD Camera alignment systems and Single/Split-field Microscope alignment system are available.

ABM Fully Auto Mask Aligner System

ABM, Inc. releases their first Fully Auto Aligner ABM/6/350/NUV/DCCI which inherits the stability and superior quality of ABM mask aligner products. With its high thoughput ability, customer can produce their product with new design and introduce into the market with shorter t The Fully-Auto System with throughput of 120-130+ WPH with max. It substrate and the alignment accuracy up to +/- 0.5 micron. The auto alignment system can be tuned to achieve the best alignment image work with different kinds of substrate, e.g. transaprent and rough su substrate.

ABM Fully Auto Mask Aligner Specifications:

Model: ABM/6/350/NUV/DCCD/FA High Productivity: Double Cassettes for loading and unloading Linear motion transfer arm for processing three substrates simultaneously, throughput of 120-150 WPH Special design of transfer arm for carrying thin, warpaged substrate Precision design of UV lightsource provides high brightness of light intensity output.

Model: ABM/6/500/NUV/DCCD/FA

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ABM Fully Auto Mask Aligner Specifications

Frontside alignment accuracy: +/-1 micron Alignment System: Split field dual CCD camera system Split field separation: 10mm to 150mm UV wavelength: NUV 365/400, DUV 220, 254 Uniform Beam Size: 6" diameter/square Beam Uniformity: < ±1% over 2" Round Area < ±2% over 4" Round Area < ±3% over 6" Round Area Substrate size: Min. 2" to Max. 6" (round) Mask size: Min. 3" to Max. 7" (squure) Operation Mode: Contact and Proximity prinitng Max. Proximity gap between mask and substrate is 300 microns

Alignment Key: Standard cross pattern Alignment stage: Electromechanical motion stage. Auto Z-planarization, Wedge compensatio and leveling.

17" LCD High resolution LCD monitor for alignment system15" Touch panel HMI displayMain controlling system: PC/PLC

ABM Mask Replicator System

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Model: ABM/6/350/NUV/MR

ABM Mask Replicator System

ABM, Inc. Stand alone exposure system includes with the NUV/DUV lightsource, power supply and manual/auto exposure controller. This product mainly focuses on single lithography process with high productivity throughput in low cost solution.

The exposure area can be 4"/6" 8" and max. up to 20" 350W 6" lightsource (NUV) 365 nm Output Intensity – 18-20 mW/cm² 400 nm Output Intensity – 35-40 mW/cm²

Main Functions:

Contact Vacuum On/Off Auto-Planarization Z-axis Proximity Gap Setting (0~6mm) N2 On/Off N2 Level adjustment LED, TFT-OLED. The mask aligner is highly reliable and stable with highly throughput. The systems are

Main Features:

Alignment System: 90-600x continuous CCD Zoom Maginification

PSS Process Sample

Case 1: NUV Printing (365nm/ 400nm/ 436nm line)

Case 2: ABM mask aligner works with thick resist

Case 3: ABM mask aligner with Ultra-thick resist

Technical Support and Service

Our cleanroom is qualified with class 100 certificate and we provide R&D and lithography service to our customers. We also have professional engineer and warehouse in China, Hong Kong and Taiwan to provide immediate service and technical support to our customers.

Options and Accessories

UV Light Intensity Meter

Tailor made Mask Holder

Tailor made Chuck

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